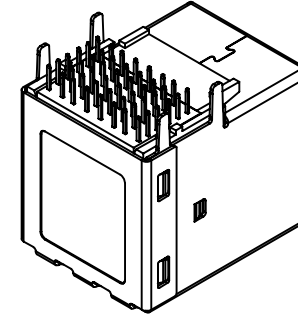
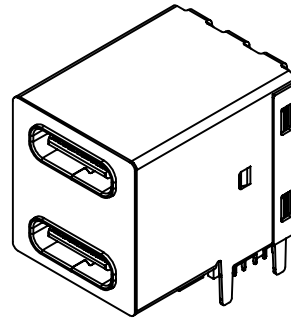




REV	DESCRIPTION	DATE	APPROVED
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NOTE:

1. MATERIAL:

- 1.1 HOUSING: LCP, UL 94V-0, COLOR- BLUE (PANTONE 300C) OR BLACK
- 1.2 BOTTOM COVER: LCP, UL 94V-0, COLOR- BLUE (PANTONE 300C) OR BLACK
- 1.3 CONTACT: C7025 (T=0.12mm); C2680 (T=0.15mm)
- 1.4 SOCKET SHELL: SUS304-1/2H (T=0.3mm)
- 1.5 FRONT MIDDLE SHELL: SUS304-1/2H (T=0.25mm)
- 1.6 REAR SHELL: SUS304-1/2H (T=0.2mm)
- 1.7 MID PLATE: SUS301-1/2H (T=0.15mm)
- 1.8 PCB: FR4

2. ELECTRICAL CHARACTERISTICS:

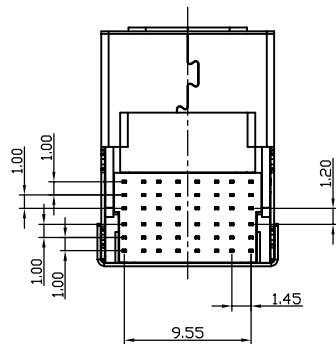
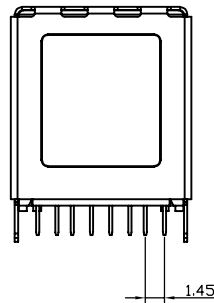
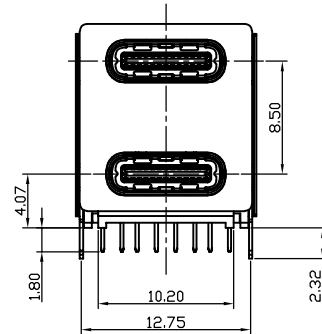
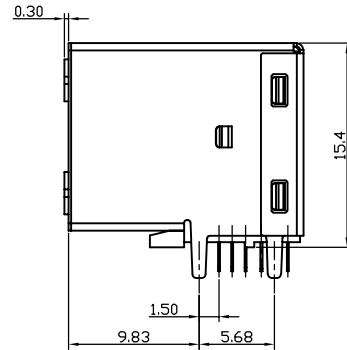
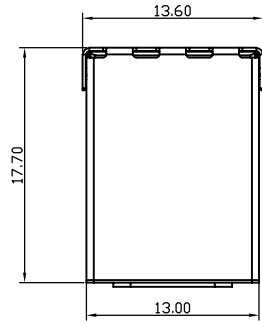
- 2.1 CONTACT RESISTANCE: 30mΩ Max FOR INITIAL. 10mΩ CHANGE AFTER TEST. MEASURE AT 20mV, 100mA.
- 2.2 CONTACT CURRENT RATING: 5A FOR COLLECTIVELY POWER SUPPLY PIN (PINA1, A4, A9, A12, B1, B4, B9, B12); 1.25A FOR VCONN PIN; 0.25A FOR OTHER SIGNAL PIN.
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE: 100V AC R. M. S.
- 2.4 INSULATION RESISTANCE 100MΩ Min
- 2.5 OPERATING TEMPERATURE: -40° C ~ 85° C

3. MECHANICAL CHARACTERISTICS:

- 3.1 MATING FORCE: 5~20 N.
- 3.2 UNMATED FORCE: 8~20N INITIAL TEST; 6~20N DURABILITY AFTER TEST
- 3.3 DURABILITY: 10,000 CYCLES

4. PLATING

- 4.1 TERMINAL CONTACT: 1u" GOLD PLATING ON CONTACT AREA, ALL OVER 50u" Min NICKEL AND 1u" Min Matte GOLD ALL OVER 50u" Min NICKEL ON SOLDER AREA
- 4.2 SHELL: 50u" Min. NICKEL ALL OVER,
- 4.3 MID PLATE: CLEAN



CUSTOMER DRAWING			东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.		
UNITS mm	SCALE 1:1	SHEET 1 OF 3	TITLE XB-TYPEC-24+24PIN-F 24PIN 板上双层母座 C+C		
PROJECTION: 		DRAW: DAP	MAT'L SEE TABLE		
GENERAL TOLERANCE 0. ±0.25 0.0 ±0.20 0.00 ±0.10 0.° ±5° 0.0° ±2°		CHECK: HWT	FINISH SEE TABLE		
		APPD: HHM	DWG. NO. 0373. TCF. 24SC. R75	PART NO. _____	SIZE A4



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USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use(SBU)	B5	CC2	Configuraaion Channel
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

RECOMMENDED PCB LAYOUT(TOP VIEW)
(DEFAULT TOLERANCE:±0.05)

CUSTOMER DRAWING			XG 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.		
UNITS	SCALE	SHEET			
mm	1:1	2 OF 3	TITLE XB-TYPEC-24+24PIN-F 24PIN 板上双层母座 C+C		
PROJECTION:		DRAW:	MAT'L SEE TABLE FINISH SEE TABLE		
GENERAL TOLERANCE		CHECK:			
0. ±0.25		HWT	DWG. NO. 0373. TCF. 24SC. R75 PART NO. _____ SIZE A4		
0.0 ±0.20		APPD:			
0.00 ±0.10		HHM			
0.° ±5°					
0.0° ±2°					

